

IN THE SPECIFICATION

Please replace the paragraph beginning on page 9, line 22, with the following rewritten paragraph:

The separating device 700 is arranged between a bottom of the process chamber 200 and the heater stage 600. The separating device 700 separates an inner space 207 of the process chamber 200, which contains the wafer 100, from a space 255 located beneath the heater stage 600. The dead volume is thereby substantially eliminated and the volume of the process space is thereby reduced.